## P3PS850BH

## Timing-Safe ${ }^{\text {TM }}$ Peak EMI Reduction IC

## Functional Description

P3PS850BH is a versatile, Timing-Safe peak EMI reduction IC. P3PS850BH accepts one input from an external reference, and locks on to it delivering a 1 x Timing-Safe output clock. P3PS850BH has a Frequency Selection (FS) control that facilitates selecting one of the two operating frequency ranges. Refer to the frequency Selection table. The device has an SSEXTR pin to select different deviations depending upon the value of an external resistor connected at this pin to GND. P3PS850BH has an MR pin for selecting one of the two Modulation Rates. PD\#/OE provides the Power Down option. Outputs will be tri-stated when power down is active.

P3PS850BH operates over a supply voltage range of 2.3 V to 3.6 V , and is available in an 8 Pin WDFN ( $2 \mathrm{~mm} \times 2 \mathrm{~mm}$ ) Package.

## General Features

- 1x , LVCMOS Timing-Safe Peak EMI Reduction
- Input Clock Frequency:
- $18 \mathrm{MHz}-72 \mathrm{MHz}$
- Output Clock Frequency( Timing-Safe):
- $18 \mathrm{MHz}-72 \mathrm{MHz}$
- Analog Frequency Deviation Selection
- Two different Modulation Rate Selection
- Power Down Option for Power Save
- Output Buffer Strength: 16 mA
- Supply Voltage: $2.3 \mathrm{~V}-3.6 \mathrm{~V}$
- 8 pin WDFN $2 \mathrm{~mm} \times 2 \mathrm{~mm}$, (TDFN) Package
- These Devices are $\mathrm{Pb}-$ Free, Halogen Free/BFR Free and are RoHS Compliant


## Application

- P3PS850BH is targeted for use in consumer electronic applications like mobile phones, Camera modules, MFP and DPF.

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$$
\begin{array}{ll}
\text { DG } & =\text { Specific Device Code } \\
\text { M } & =\text { Date Code } \\
\text { - } & =\text { Pb-Free Device }
\end{array}
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ORDERING INFORMATION
See detailed ordering and shipping information in the package dimensions section on page 11 of this data sheet.

## P3PS850BH



Figure 1. Block Diagram

Table 1. PIN DESCRIPTION

| Pin\# | Pin Name | Type | Description |
| :---: | :---: | :---: | :--- |
| 1 | CLKIN | I | External reference Clock input. |
| 2 | PD\# / OE | I | Power Down. Pull LOW to enable Power Down. Outputs will be tri-stated when power down is en- <br> abled. Pull HIGH to disable power down and enable output. NO default state. |
| 3 | FS | I | Frequency Select .NO default state. Refer to the Frequency Selection table |
| 4 | GND | P | Ground |
| 5 | ModOUT | O | Buffered modulated Timing-Safe clock output |
| 6 | MR | I | Modulation Rate Select. When LOW, selects Low Modulation Rate. Selects High <br> Modulation Rate when pulled HIGH. Has an internal pull-up resistor. |
| 7 | SSEXTR | I | Analog Deviation Selection through external resistor to GND. |
| 8 | $\mathrm{~V}_{\mathrm{DD}}$ | P | Supply Voltage |

Table 2. FREQUENCY SELECTION TABLE

| FS | Frequency (MHz) |
| :---: | :---: |
| 0 | $18-36$ |
| 1 | $36-72$ |

Table 3. OPERATING CONDITIONS

| Symbol | Parameter | Min | Max | Unit |
| :---: | :--- | :---: | :---: | :---: |
| $\mathrm{V}_{\mathrm{DD}}$ | Supply Voltage | 2.3 | 3.6 | V |
| $\mathrm{~T}_{\mathrm{A}}$ | Operating Temperature | -20 | +85 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{C}_{\mathrm{L}}$ | Load Capacitance |  | 15 | pF |
| $\mathrm{C}_{\mathrm{IN}}$ | Input Capacitance |  | 7 | pF |

Table 4. ABSOLUTE MAXIMUM RATING

| Symbol | Parameter | Rating | Unit |
| :---: | :--- | :---: | :---: |
| $\mathrm{V}_{\mathrm{DD},} \mathrm{V}_{\text {IN }}$ | Voltage on any input pin with respect to Ground | -0.5 to +4.6 | V |
| $\mathrm{~T}_{\mathrm{STG}}$ | Storage temperature | -65 to +125 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{T}_{\mathrm{S}}$ | Max. Soldering Temperature (10 sec) | 260 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{T}_{\mathrm{J}}$ | Junction Temperature | 150 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{T}_{\mathrm{DV}}$ | Static Discharge Voltage (As per JEDEC STD22-A114-B) | 2 | kV |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 5. DC ELECTRICAL CHARACTERISTICS

| Symbol | Parameter | Test Conditions |  | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $V_{\text {DD }}$ | Supply Voltage |  |  | 2.3 | 2.7 | 3.6 | V |
| $\mathrm{V}_{\mathrm{IH}}$ | Input HIGH Voltage |  |  | 0.65 * $\mathrm{V}_{\mathrm{DD}}$ |  |  | V |
| $\mathrm{V}_{\mathrm{IL}}$ | Input LOW Voltage |  |  |  |  | 0.35 * V ${ }_{\text {DD }}$ | V |
| $\mathrm{IIH}^{\text {I }}$ | Input HIGH Current | $\mathrm{V}_{\text {IN }}=\mathrm{V}_{\mathrm{DD}}$ |  |  |  | 10 | $\mu \mathrm{A}$ |
| IIL | Input LOW Current | $\mathrm{V}_{\text {IN }}=0 \mathrm{~V}$ for MR pin |  |  |  | 10 | $\mu \mathrm{A}$ |
| $\mathrm{V}_{\mathrm{OH}}$ | Output HIGH Voltage | $\mathrm{IOH}^{\prime}=-16 \mathrm{~mA}$ |  | 0.75 * $\mathrm{V}_{\mathrm{DD}}$ |  |  | V |
| $\mathrm{V}_{\text {OL }}$ | Output LOW Voltage | $\mathrm{l} \mathrm{OL}=16 \mathrm{~mA}$ |  |  |  | 0.25 * V ${ }_{\text {DD }}$ | V |
| $\mathrm{I}_{\mathrm{cc}}$ | Static Supply Current | PD\#/OE pin pulled to GND |  |  |  | 10 | $\mu \mathrm{A}$ |
| $\mathrm{I}_{\mathrm{DD}}$ | Dynamic Supply Current | Unloaded Output | FS = 0, @ 18 MHz |  | 6 | 10 | mA |
|  |  |  | FS = 0, @ 24 MHz |  | 7 | 12 |  |
|  |  |  | FS = 0, @ 36 MHz |  | 10 | 17 |  |
|  |  |  | FS = 1, @ 36 MHz |  | 9 | 14 |  |
|  |  |  | FS = 1, @ 48 MHz |  | 11 | 19 |  |
|  |  |  | FS = 1, @ 72 MHz |  | 16 | 28 |  |
| $\mathrm{Z}_{0}$ | Output Impedance |  |  |  | 13 |  | $\Omega$ |

Table 6. AC ELECTRICAL CHARACTERISTICS

| Parameter | Test Conditions | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: |
| Input Frequency | $F S=0$ | 18 | 24 | 36 | MHz |
|  | $F S=1$ | 36 | 48 | 72 |  |
| ModOUT | $F S=0$ | 18 | 24 | 36 |  |
|  | $\mathrm{FS}=1$ | 36 | 48 | 72 |  |
| Duty Cycle (Note 1 and 2) | Measured at $\mathrm{V}_{\mathrm{DD}} / 2$ | 45 | 50 | 55 | \% |
| Rise Time (Note 1 and 2) | Measured between 20\% to 80\% |  | 0.8 | 1.2 | ns |
| Fall Time (Note 1 and 2) | Measured between 80\% to 20\% |  | 0.8 | 1.2 | ns |

1. All parameters are specified with 15 pF loaded output.
2. Parameter is guaranteed by design and characterization. Not $100 \%$ tested in production.

## P3PS850BH

Table 6. AC ELECTRICAL CHARACTERISTICS

| Parameter | Test Conditions |  | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Cycle-to-Cycle Jitter (Note 2) | Unloaded output with SSEXTR pin OPEN | FS $=0,18 \mathrm{MHz}$ |  | $\pm 250$ | $\pm 350$ | ps |
|  |  | FS $=0,24 \mathrm{MHz}$ |  | $\pm 150$ | $\pm 225$ |  |
|  |  | FS $=0,36 \mathrm{MHz}$ |  | $\pm 75$ | $\pm 125$ |  |
|  |  | FS $=1,36 \mathrm{MHz}$ |  | $\pm 150$ | $\pm 200$ |  |
|  |  | FS $=1,48 \mathrm{MHz}$ |  | $\pm 100$ | $\pm 150$ |  |
|  |  | FS $=1,72 \mathrm{MHz}$ |  | $\pm 75$ | $\pm 125$ |  |
| PLL Lock Time (Note 2) | Stable power supp ted on CLKIN pin, to High | , valid clock presenD\# toggled from Low |  |  | 1 | ms |

1. All parameters are specified with 15 pF loaded output.
2. Parameter is guaranteed by design and characterization. Not $100 \%$ tested in production.

## P3PS850BH

DEVIATION VERSUS SSEXTR RESISTANCE CHARTS


Figure 2. Deviation vs. SSEXTR @ 18 MHz
(FS = 0)


Figure 4. Deviation vs. SSEXTR @ 27 MHz ( $\mathrm{FS}=0$ )


Figure 3. Deviation vs. SSEXTR @ 24 MHz
( $\mathrm{FS}=0$ )


Figure 5. Deviation vs. SSEXTR @ 30 MHz
( $\mathrm{FS}=0$ )


Figure 6. Deviation vs. SSEXTR @ 36 MHz
( $\mathrm{FS}=0$ )

## P3PS850BH

DEVIATION VERSUS SSEXTR RESISTANCE CHARTS


Figure 7. Deviation vs. SSEXTR @ 36 MHz
( $\mathrm{FS}=1$ )


Figure 9. Deviation vs. SSEXTR @ 54 MHz ( $\mathrm{FS}=1$ )


Figure 8. Deviation vs. SSEXTR @ 48 MHz ( $\mathrm{FS}=1$ )


Figure 10. Deviation vs. SSEXTR @ 60 MHz
( $\mathrm{FS}=1$ )


Figure 11. Deviation vs. SSEXTR @ 72 MHz ( $\mathrm{FS}=1$ )

## P3PS850BH

TSKEW VERSUS SSEXTR RESISTANCE CHARTS


Figure 12. Tskew vs. SSEXTR @ 18 MHz
( $\mathrm{FS}=0$ )


Figure 14. Tskew vs. SSEXTR @ 27 MHz ( $\mathrm{FS}=0$ )


Figure 16. Tskew vs. SSEXTR @ 36 MHz
(FS = 1)


Figure 13. Tskew vs. SSEXTR @ 24 MHz
(FS = 0)


Figure 15. Tskew vs. SSEXTR @ 36 MHz
( $\mathrm{FS}=0$ )


Figure 17. Tskew vs. SSEXTR @ 48 MHz
(FS = 1)


Figure 18. Tskew vs. SSEXTR @ 54 MHz
( $\mathrm{FS}=1$ )


Figure 19. Tskew vs. SSEXTR @ 72 MHz
( $\mathrm{FS}=1$ )

MINIMUM SSEXTR RESISTANCE VERSUS FREQUENCY(FOR TIMING-SAFE OPERATION) CHARTS


Figure 20. Frequency vs. Resistance ( $\mathrm{FS}=0$ )


Figure 21. Frequency vs. Resistance ( $\mathrm{FS}=1$ )

NOTE: Device-to-Device variation of Deviation and Tskew is $\pm 10 \%$

## SWITCHING WAVEFORMS



Figure 22. Duty Cycle Timing


Figure 23. Output Rise/Fall Time


Figure 24. Input-Output Skew


Figure 25. Typical Example of Timing-Safe Waveform

## P3PS850BH



NOTE: Refer Pin Description table for Functionality details.
Figure 26. Typical Application Schematic

## P3PS850BH

## PCB Layout Recommendation

For optimum device performance, following guidelines are recommended.

- Dedicated $\mathrm{V}_{\mathrm{DD}}$ and GND planes.
- The device must be isolated from system power supply noise. A $0.1 \mu \mathrm{~F}$ and a $2.2 \mu \mathrm{~F}$ decoupling capacitor should be mounted on the component side of the board as close to the $\mathrm{V}_{\mathrm{DD}}$ pin as possible. No vias should be used between the decoupling capacitor and $\mathrm{V}_{\mathrm{DD}}$ pin. The PCB trace to $\mathrm{V}_{\mathrm{DD}}$ pin and the ground via should be kept as short as possible. All the $\mathrm{V}_{\mathrm{DD}}$ pins should have decoupling capacitors.
- In an optimum layout all components are on the same side of the board, minimizing vias through other signal layers.

A typical layout is shown in Figure 27.


Figure 27.

ORDERING INFORMATION

| Part Number | Top <br> Marking | Temperature | Package Type | Shipping ${ }^{\dagger}$ |
| :---: | :---: | :---: | :---: | :---: |
| P3PS850BHG-08CR | DG | $-20^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ | $8-$ Pin (2 mm x2 mm) WDFN(TDFN) | $3000 /$ Tape \& Reel |

$\dagger$ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*A "microdot" placed at the end of last row of marking or just below the last row toward the center of package indicates $\mathrm{Pb}-\mathrm{Free}$.

## P3PS850BH

## PACKAGE DIMENSIONS

WDFN8 2x2, 0.5P
CASE 511AQ
ISSUE A


DETAIL A
OPTIONAL constructions

EXPOSED Cu MOLD CMPD


BOTTOM VIEW

DETAIL B
OPTIONAL construction
notes:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED

TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL

| DIM | MILLIMETERS |  |
| :---: | :---: | :---: |
|  | MIN | MAX |
| A | 0.70 | 0.80 |
| A1 | 0.00 | 0.05 |
| A3 | 0.20 REF |  |
| b | 0.20 |  |
| D | 2.00 BSC |  |
| E | 2.00 BSC |  |
| e | 0.50 |  |
| BSC |  |  |
| L | 0.50 | 0.60 |
| L1 | --- | 0.15 |

RECOMMENDED SOLDERING FOOTPRINT*
*For additional information on our $\mathrm{Pb}-$ Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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